

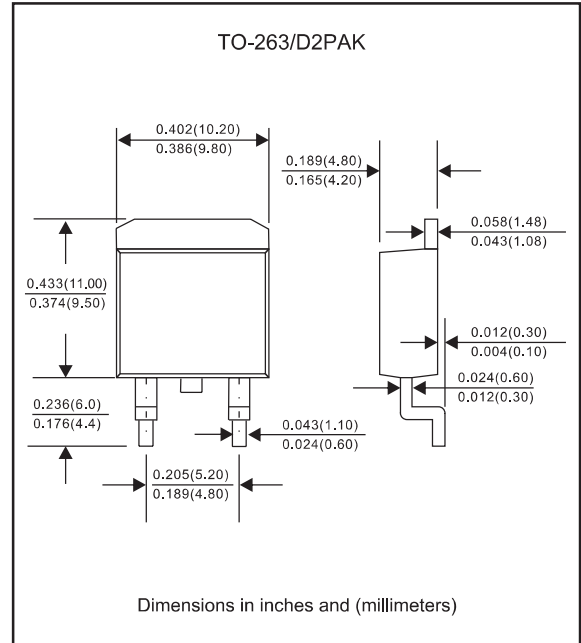
Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low power loss, high efficiency.
- High current capability, low forward voltage drop.
- High surge capability.
- Guardring for overvoltage protection.
- Ultra high-speed switching.
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, TO-263 / D2PAK
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any

Package outline



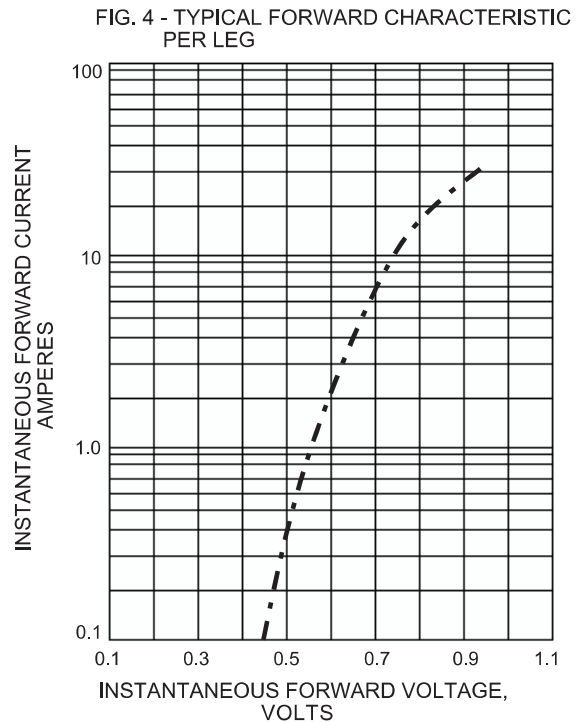
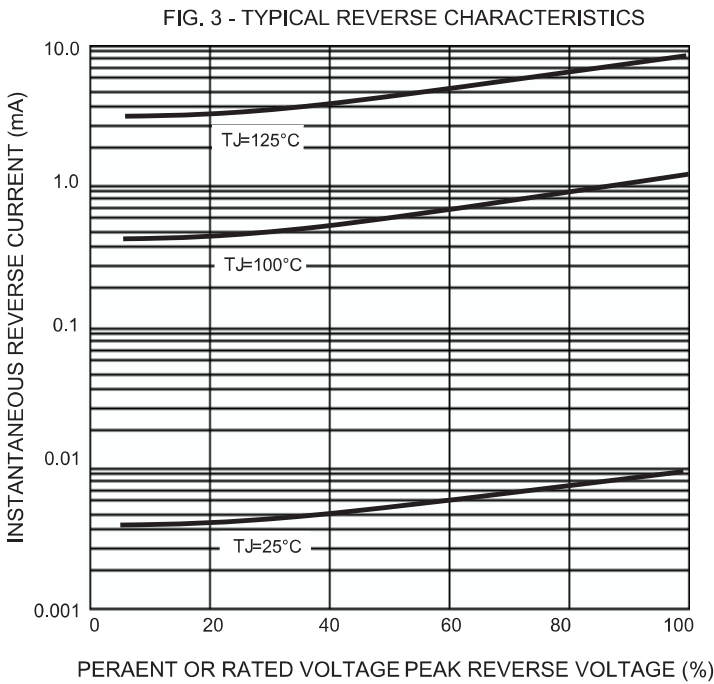
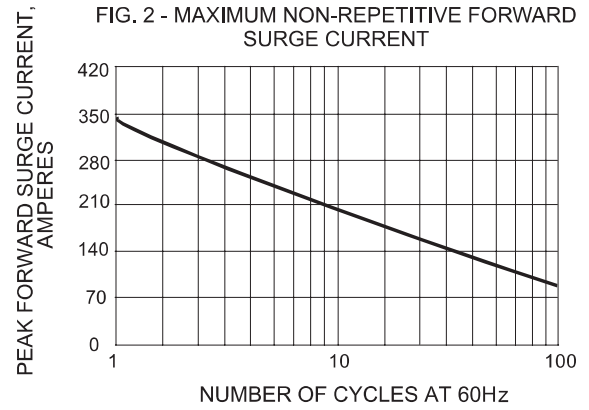
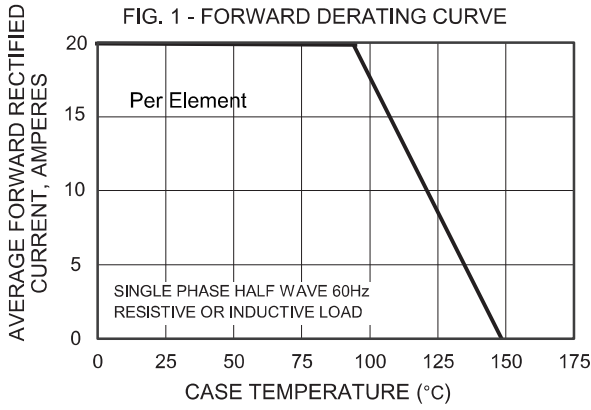
Maximum ratings and Electrical Characteristics (AT T_A=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I _O			40.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I _{FSM}			350	A
Reverse current	V _R = V _{RRM} T _J = 25°C	I _R			0.1	mA
	V _R = V _{RRM} T _J = 125°C				20	
Thermal resistance	Junction to case	R _{θJC}		1.6		°C/W
Storage temperature		T _{STG}	-65		+175	°C

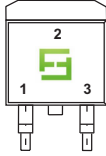
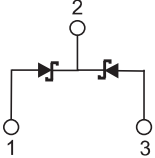
SYMBOLS	V _{RRM} ^{*1} (V)	V _{RMS} ^{*2} (V)	V _R ^{*3} (V)	V _F ^{*4} (V)	Operating temperature T _J , (°C)
MBRB41H100CTT4G	100	70	100	0.83	-55 to +150

- *1 Repetitive peak reverse voltage
- *2 RMS voltage
- *3 Continuous reverse voltage
- *4 Maximum forward voltage
IF = 20.0A, 25°C

Rating and characteristic curves



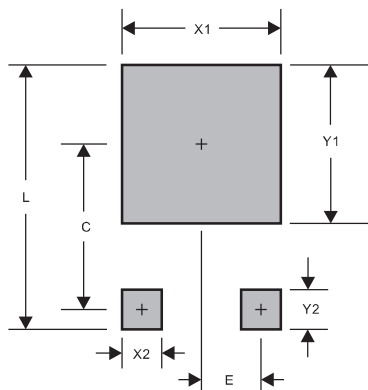
Pinning information

Pin	Simplified outline	Symbol
Pin1 anode Pin2 cathode Pin3 anode		

Marking

Type number	Marking code
MBRB41H100CTT4G	B41H100G

Suggested solder pad layout



PACKAGE	D2PAK
C	0.374(9.50)
E	0.098(2.50)
L	0.665(16.90)
X1	0.425(10.80)
X2	0.071(1.80)
Y1	0.449(11.40)
Y2	0.138(3.50)

Dimensions in inches and (millimeters)

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tP)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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